

● General Description

The AGM210MAP combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

This device is ideal for load switch and battery protection applications.

● Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

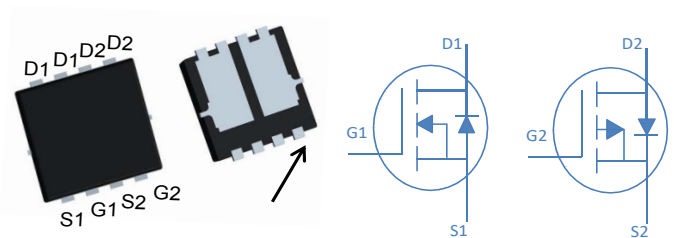
● Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

Product Summary

BVDSS	RDSON	ID
20V	11mΩ	25A
-20V	18mΩ	-25A

PDFN3.3*3.3 Pin Configuration



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGM210MAP	AGM210MAP	PDFN3.3*3.3	330mm	12mm	5000

Table 1. Absolute Maximum Ratings (Tc=25°C)

Symbol	Parameter	Rating		Units
		N-Ch	P-Ch	
V_{DS}	Drain-Source Voltage ($V_{GS}=0V$)	20	-20	V
V_{GS}	Gate-Source Voltage ($V_{DS}=0V$)	±20	±20	V
I_D	Drain Current-Continuous(TC=25°C) ^(Note 1)	25	-25	A
	Drain Current-Continuous(TC=100°C)	18	-16	A
IDM (pluse)	Drain Current-Continuous@ Current-Pulsed ^(Note 2)	70	-50	A
P_D	Total Power Dissipation(TC=25°C)	35	30.8	W
	Total Power Dissipation(TC=100°C)	14	13	W
EAS	Avalanche energy ^(Note 3)	72	59	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	-55 To 150	°C

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	3.5	°C/W

Table 3. N- Channel Electrical Characteristics (TA=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=250μA	20	--	--	V
IDSS	Zero Gate Voltage Drain Current	VDS=20V,VGS=0V	--	--	1	μA
IGSS	Gate-Body Leakage Current	VGS=±12V,VDS=0V	--	--	±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS,ID=250μA	0.4	0.7	1.0	V
gFS	Forward Transconductance	VDS=5V,ID=5A	--	9	--	S
RDS(on)	Drain-Source On-State Resistance	VGS=4.5V, ID=4A	--	11	16	mΩ
		VGS=2.5V, ID=3A	--	15	20	mΩ
Dynamic Characteristics						
Ciss	Input Capacitance	VDS=10V,VGS=0V, F=1MHZ	--	950	--	pF
Coss	Output Capacitance		--	150	--	pF
Crss	Reverse Transfer Capacitance		--	99	--	pF
Rg	Gate resistance	VGS=0V, VDS=0V,f=1.0MHz	--	--	--	Ω
Switching Times						
td(on)	Turn-on Delay Time	VGS=4.5V,VDS=10V, ID=4A,RGEN=3.3Ω	--	4.0	--	nS
tr	Turn-on Rise Time		--	25	--	nS
td(off)	Turn-Off Delay Time		--	32	--	nS
tf	Turn-Off Fall Time		--	26	--	nS
Qg	Total Gate Charge	VGS=4.5V, VDS=10V, ID=2A	--	23	--	nC
Qgs	Gate-Source Charge		--	2.5	--	nC
Qgd	Gate-Drain Charge		--	4.2	--	nC
Source-Drain Diode Characteristics						
ISD	Source-Drain Current(Body Diode)		--	--	25	A
VSD	Forward on Voltage	VGS=0V,IS=4A	--	--	1.2	V
trr	Reverse Recovery Time	IF=4A , di/dt=100A/μs ,	--	18	--	ns
Qrr	Reverse Recovery Charge	TJ=25°C	--	9.5	--	nc

Notes 1.The maximum current rating is package limited.

Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 3.EAS condition: TJ=25°C

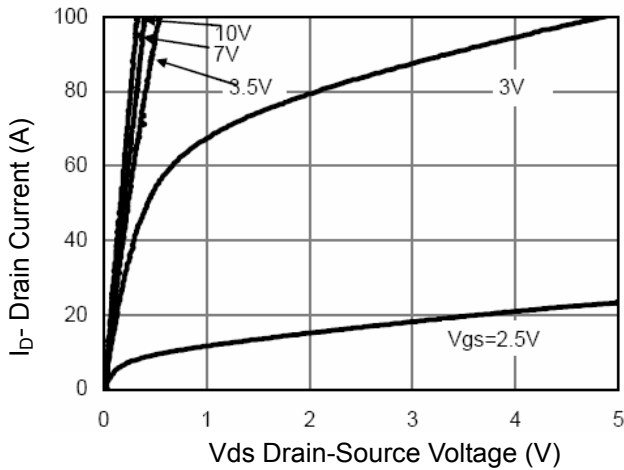
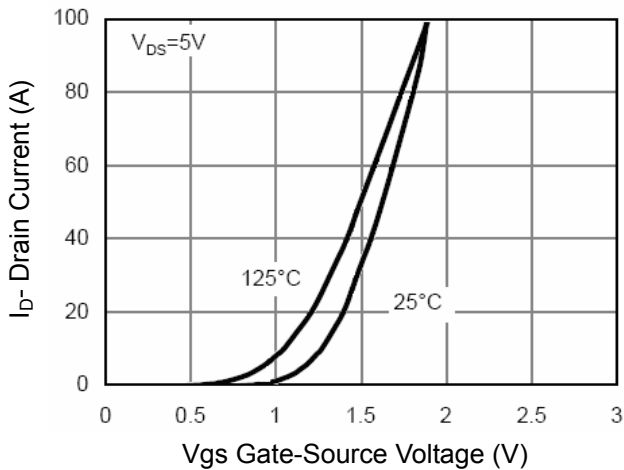
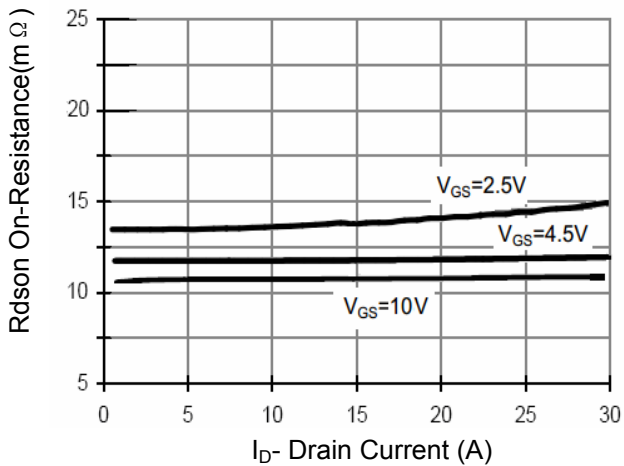
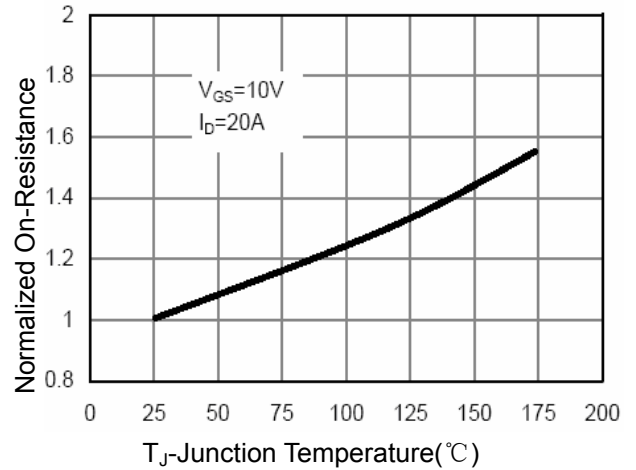
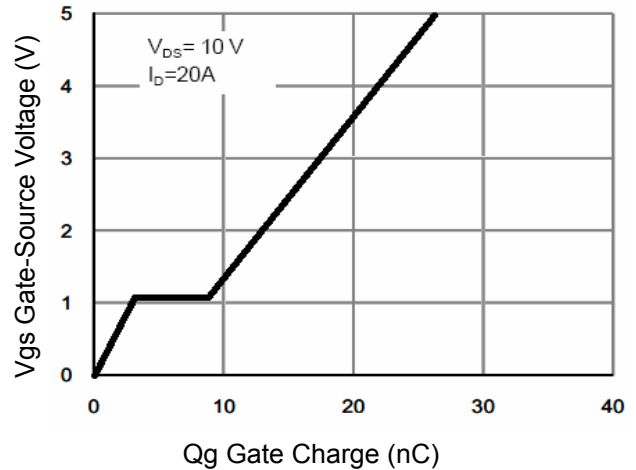
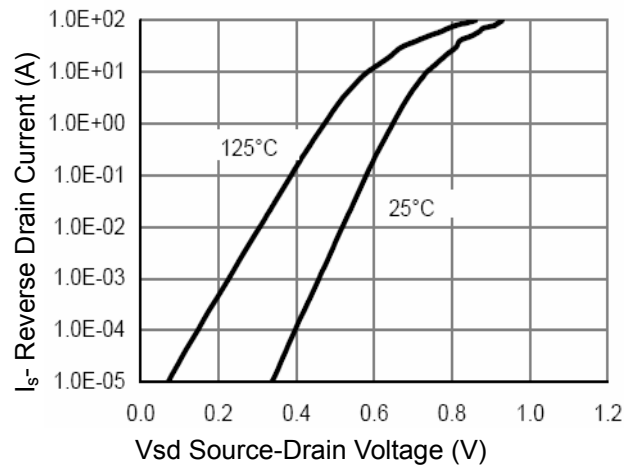
Table 3. P-Channel Electrical Characteristics (TA=25°C unless otherwise noted)

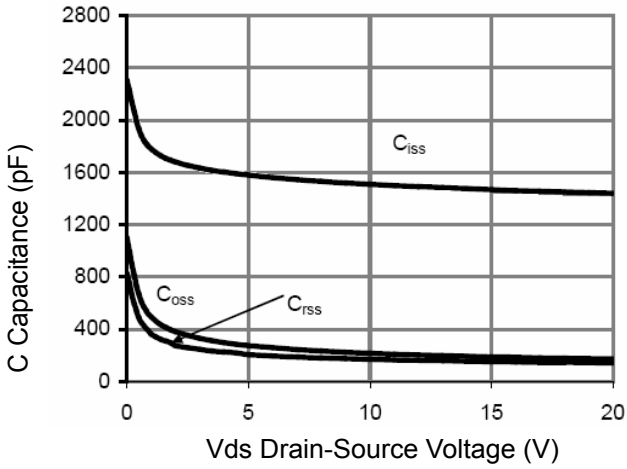
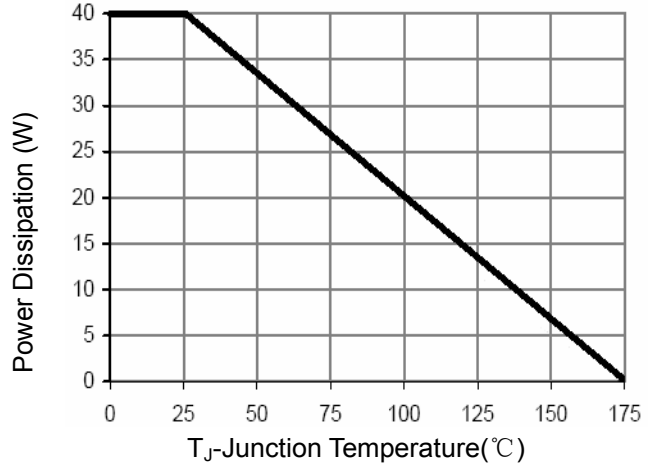
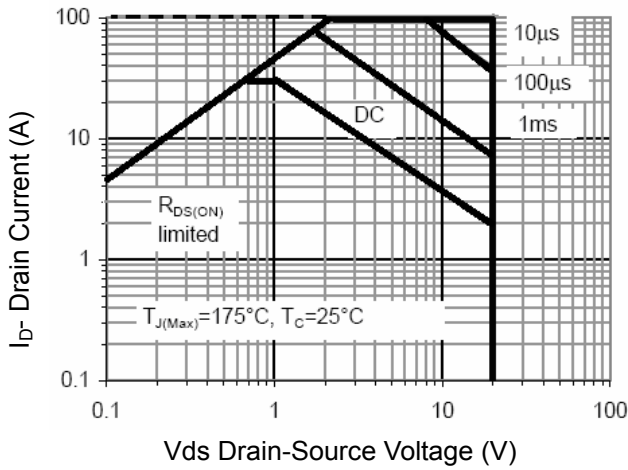
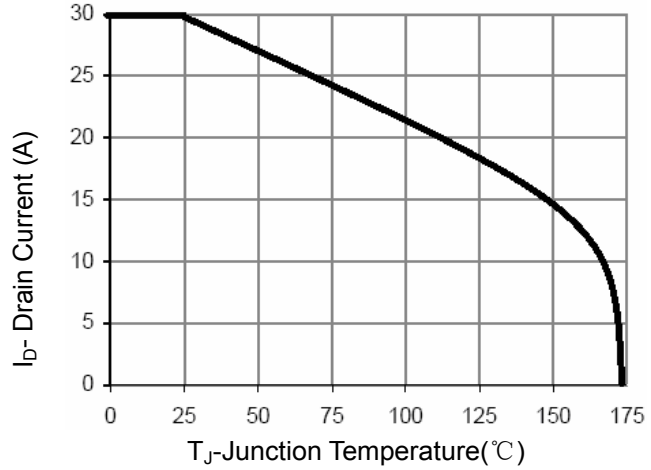
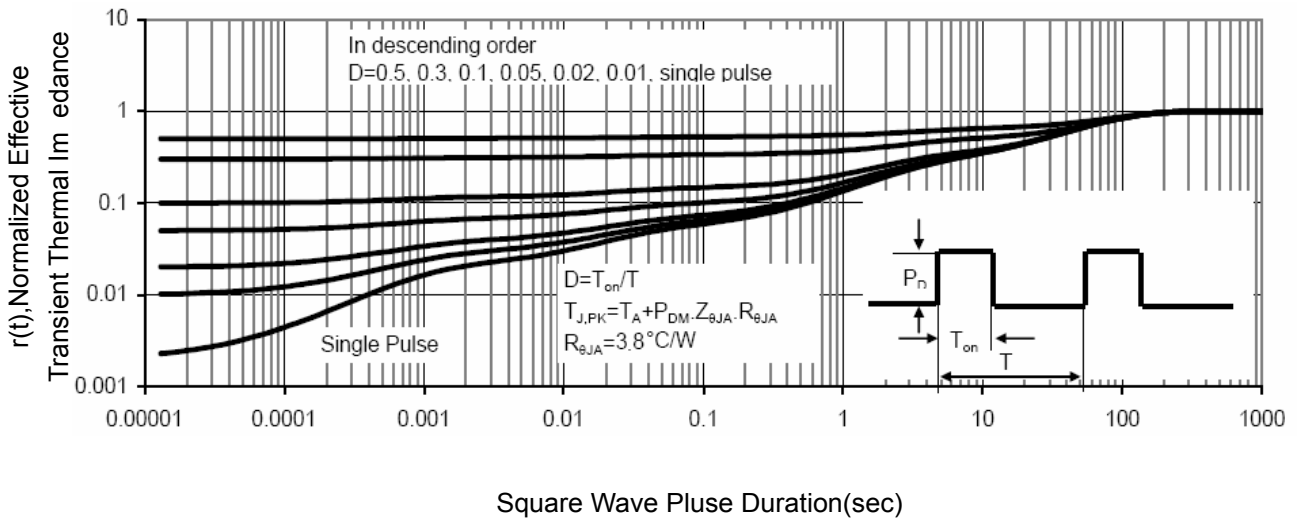
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=-250μA	-20	--	--	V
IDSS	Zero Gate Voltage Drain Current	VDS=-20V,VGS=0V	--	--	-1	μA
IGSS	Gate-Body Leakage Current	VGS=±12V,VDS=0V	--	--	±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS,ID=-250μA	-0.5	-0.7	-1.0	V
gFS	Forward Transconductance	VDS=-5V,ID=-4A	--	7	--	S
RDS(on)	Drain-Source On-State Resistance	VGS=-10V, ID=-3A	--	18	25	mΩ
		VGS=-4.5V, ID=-2A	--	25	32	mΩ
Dynamic Characteristics						
Ciss	Input Capacitance	VDS=-10V,VGS=0V, F=1MHZ	--	900	--	pF
Coss	Output Capacitance		--	170	--	pF
Crss	Reverse Transfer Capacitance		--	140	--	pF
Rg	Gate resistance	VGS=0V, VDS=0V,f=1.0MHz	--	--	--	Ω
Switching Times						
td(on)	Turn-on Delay Time	VGS=-4.5V,VDS=-10V, ID=-3A,REGEN=1Ω	--	7	--	nS
tr	Turn-on Rise Time		--	25	--	nS
td(off)	Turn-Off Delay Time		--	74	--	nS
tf	Turn-Off Fall Time		--	10	--	nS
Qg	Total Gate Charge	VGS=-4.5V, VDS=-10V, ID=-2A	--	16	--	nC
Qgs	Gate-Source Charge		--	26	--	nC
Qgd	Gate-Drain Charge		--	31	--	nC
Source-Drain Diode Characteristics						
ISD	Source-Drain Current(Body Diode)		--	--	-25	A
VSD	Forward on Voltage	VGS=0V,IS=-3A	--	--	-1.2	V
trr	Reverse Recovery Time	IF=-3A , dI/dt=100A/μs , TJ=25°C	--	11	--	ns
Qrr	Reverse Recovery Charge		--	4	--	nc

Notes 1.The maximum current rating is package limited.

Notes2.Repetitive Rating: Pulse width limited by maximum junction temperature Notes

3.EAS condition: TJ=25°C

Typical Electrical and Thermal Characteristics (Curves)

Figure 1 Output Characteristics

Figure 2 Transfer Characteristics

Figure 3 Rdson- Drain Current

Figure 4 Rdson-Junction Temperature

Figure 5 Gate Charge

Figure 6 Source- Drain Diode Forward


Figure 7 Capacitance vs Vds

Figure 9 Power De-rating

Figure 8 Safe Operation Area

Figure 10 Current De-rating

Figure 11 Normalized Maximum Transient Thermal Impedance

Typical Electrical and Thermal Characteristics

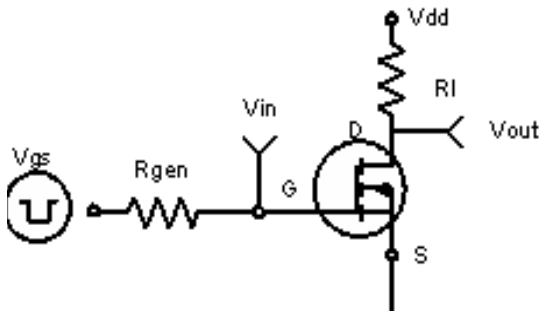


Figure 1: Switching Test Circuit

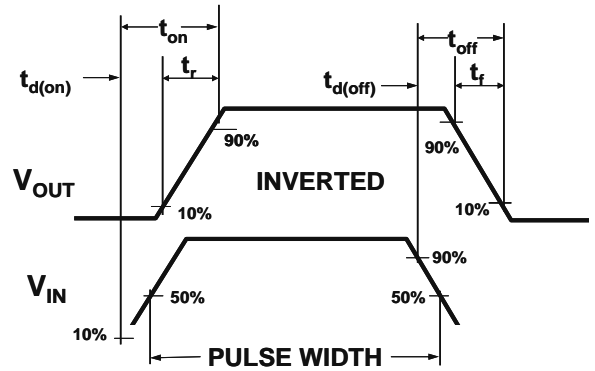


Figure 2: Switching Waveforms

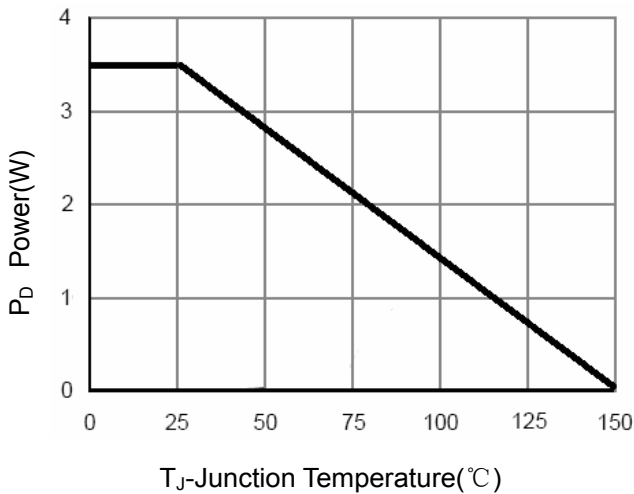


Figure 3 Power Dissipation

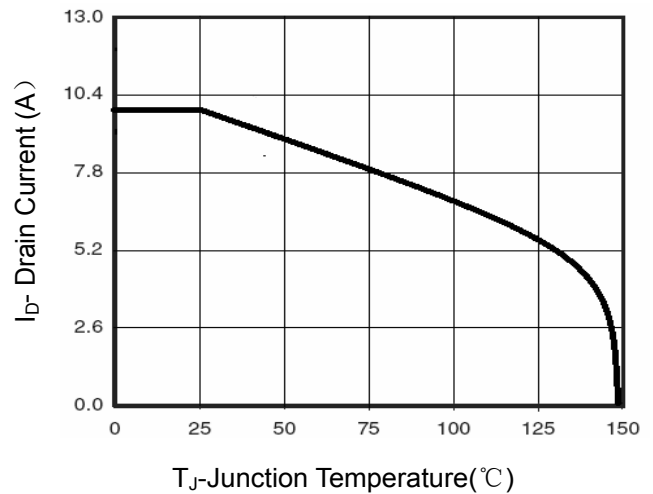


Figure 4 Drain Current

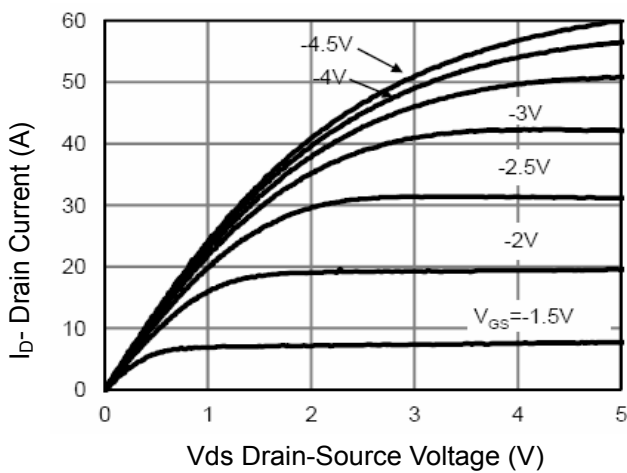


Figure 5 Output Characteristics

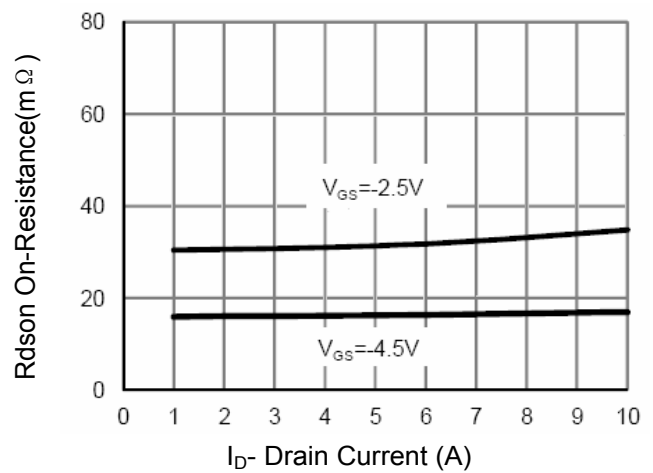
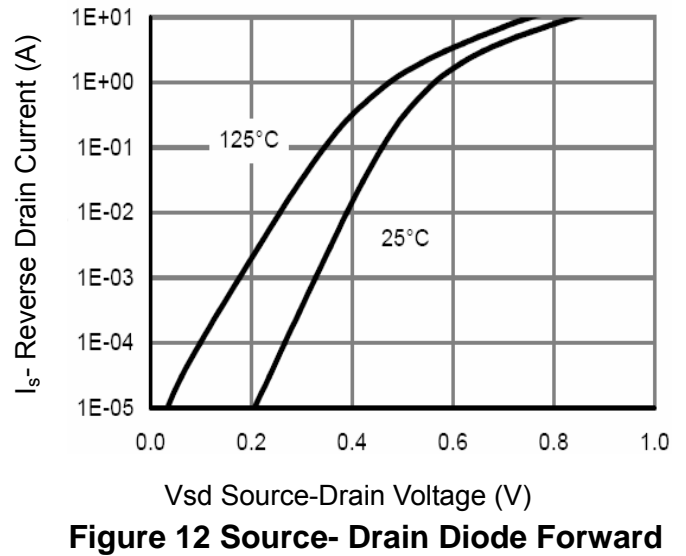
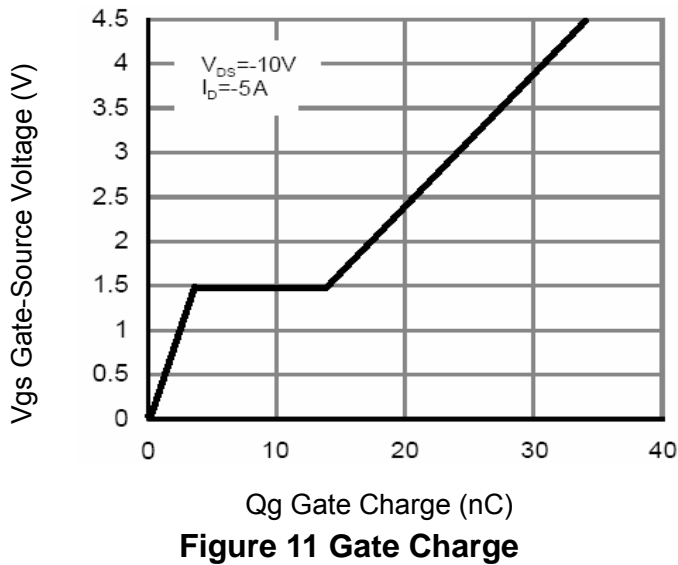
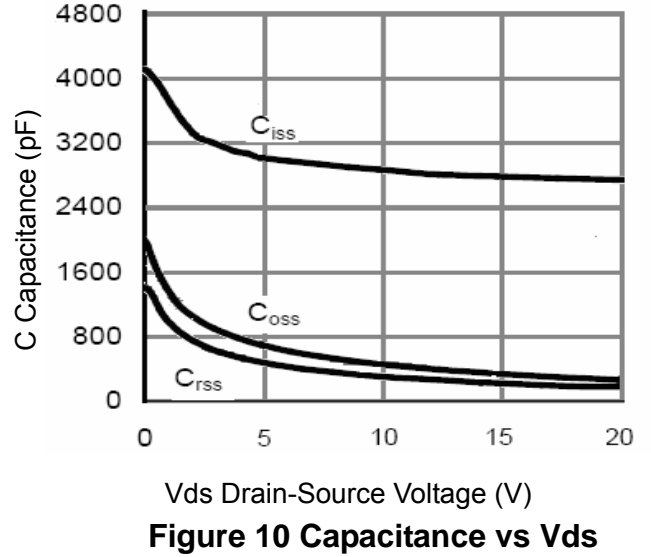
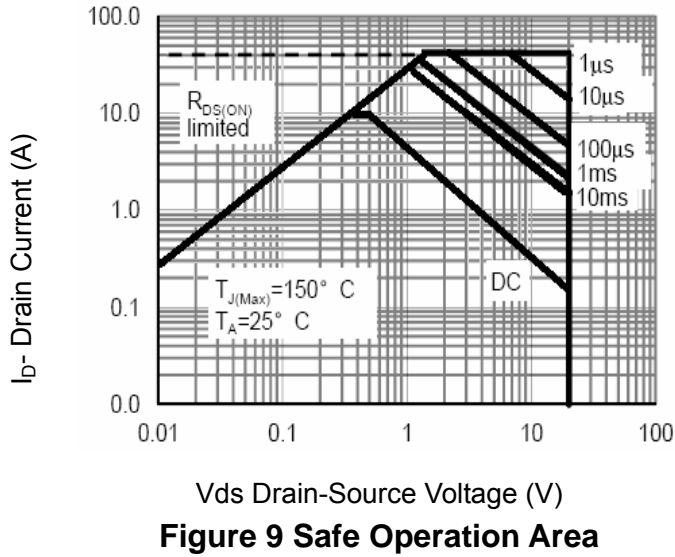
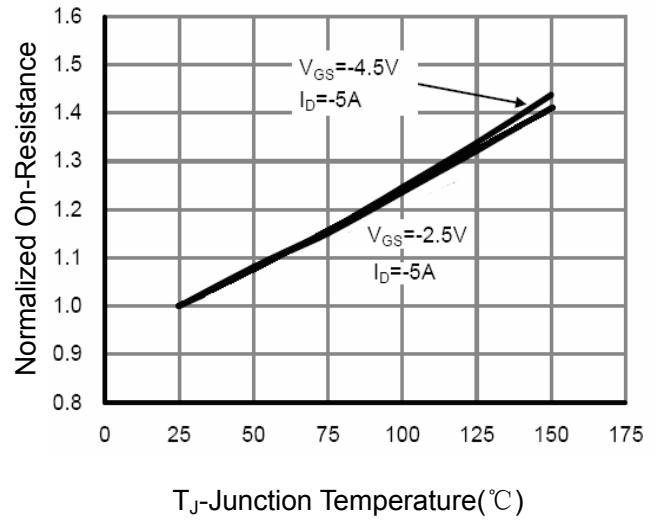
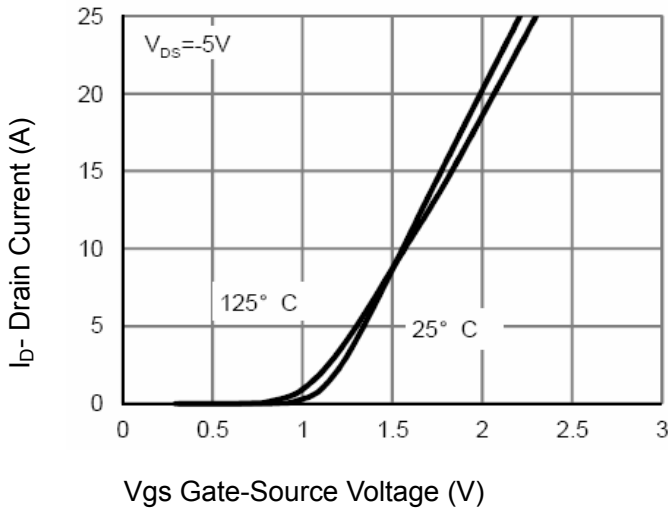


Figure 6 Drain-Source On-Resistance



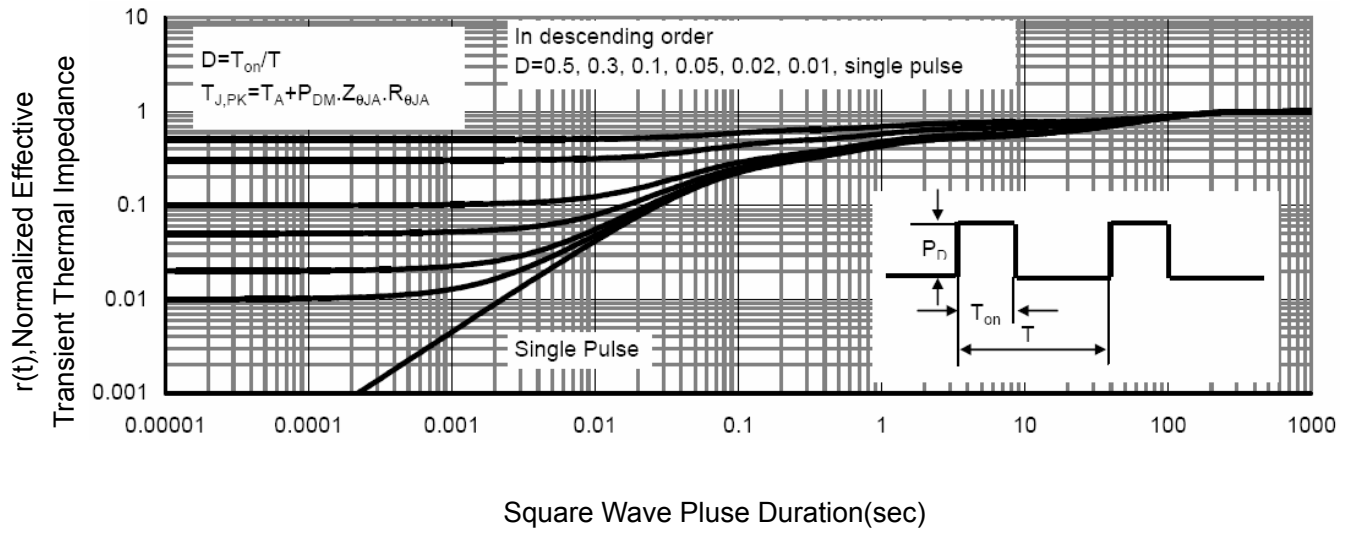
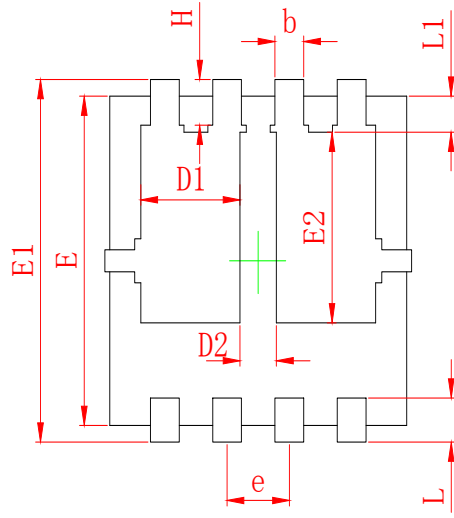
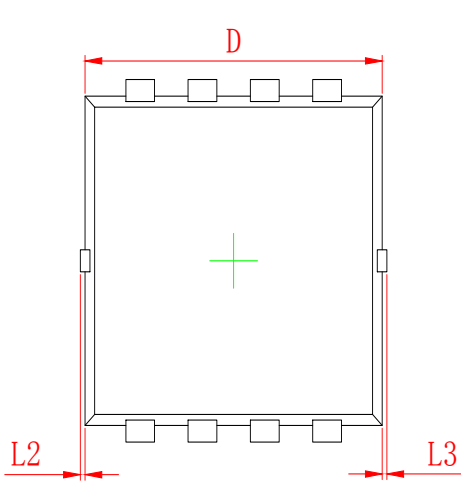
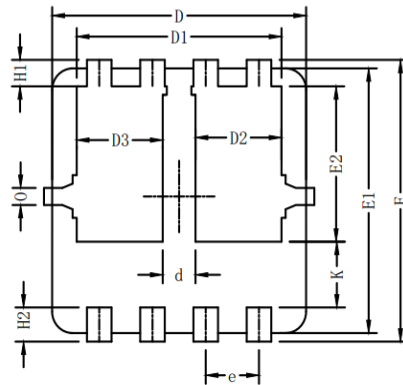
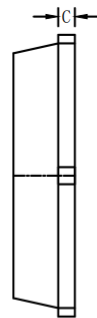
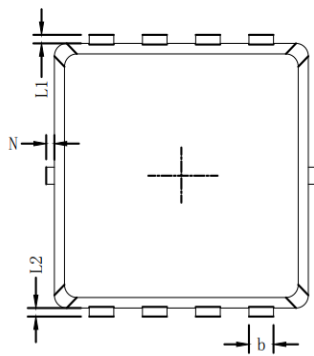
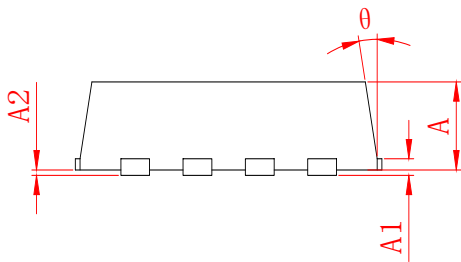


Figure 13 Normalized Maximum Transient Thermal Impedance

●Dimensions (PDFN3.3×3.3)


SYMBOL	MILLIMETER	
	MIN	MAX
A	0.700	0.900
A1	0.152 REF.	
A2	0 [~] 0.05	
D	3.000	3.200
D1	0.935	1.135
D2	0.280	0.480
E	2.900	3.100
E1	3.150	3.450
E2	1.535	1.935
b	0.200	0.400
e	0.550	0.750
L	0.300	0.500
L1	0.180	0.480
L2	0 [~] 0.100	
L3	0 [~] 0.100	
H	0.315	0.515
θ	8°	12°



Symbols	Millimeters		
	MIN.	NOM.	MAX.
A	0.65	0.75	0.85
b	0.25	0.30	0.35
C	0.15	0.20	0.25
D	3.00	3.10	3.20
D1	2.40	2.50	2.60
D2/D3	1.00	1.05	1.10
d	0.30	0.40	0.50
E	3.20	3.30	3.40
E1	3.00	3.10	3.20
E2	1.72	1.82	1.92
e	0.65 BSC.		
H1	0.21	0.31	0.41
H2	0.30	0.40	0.50
K	0.67	0.77	0.87
L1/L2	0.10 REF.		
θ	11°	12°	13°
N	0	-	0.15
0	0.2 REF.		


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